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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC138

3-to-8-line Decoder/Demultiplexer



ADE-205-444 (Z)

1st. Edition

Sep. 2000

Description

The HD74HC138 has 3 binary select inputs (A, B and C). If the device is enabled these inputs determine which one of the eight normally high outputs will go low. Two active low and one active high enables (G_1 , G_{2A} and G_{2B}) are provided to ease the cascading of decoders.

Features

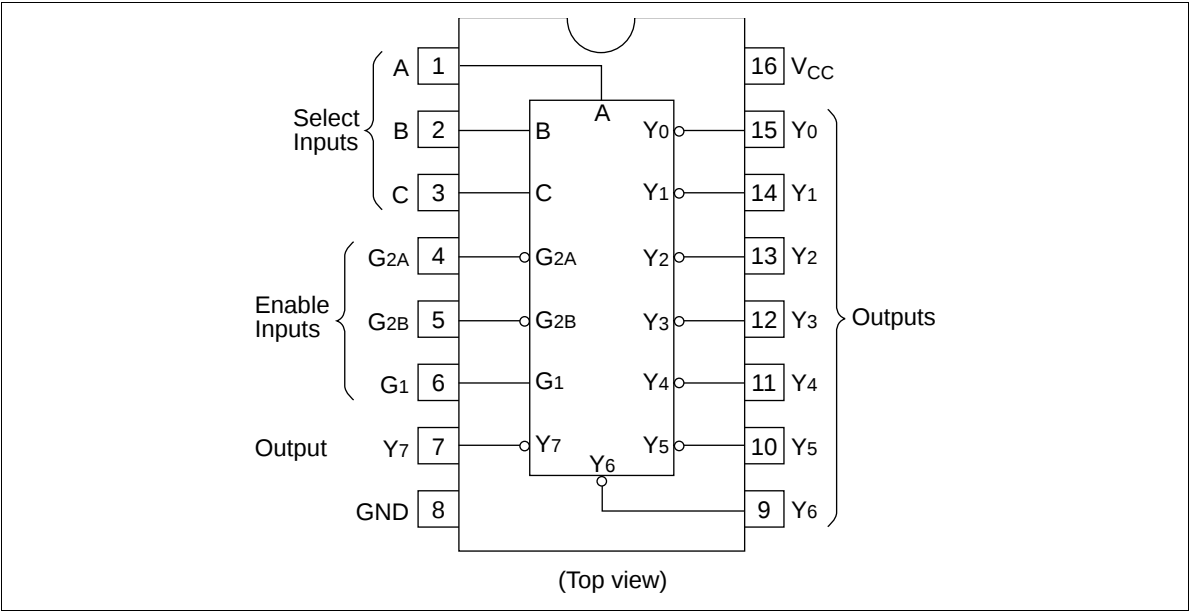
- High Speed Operation: t_{pd} (A, B, C to Y) = 16.5 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ V to 6 V
- Low Input Current: $1 \mu A$ max
- Low Quiescent Supply Current: I_{CC} (static) = $4 \mu A$ max ($T_a = 25^\circ C$)

Function Table

Inputs

[illegible]

Pin Arrangement



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V _{IL}	2.0	—	—	0.5	—	0.5	V	
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		
		6.0	5.68	—	—	5.63	—		
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		
		6.0	—	—	0.26	—	0.33		
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA

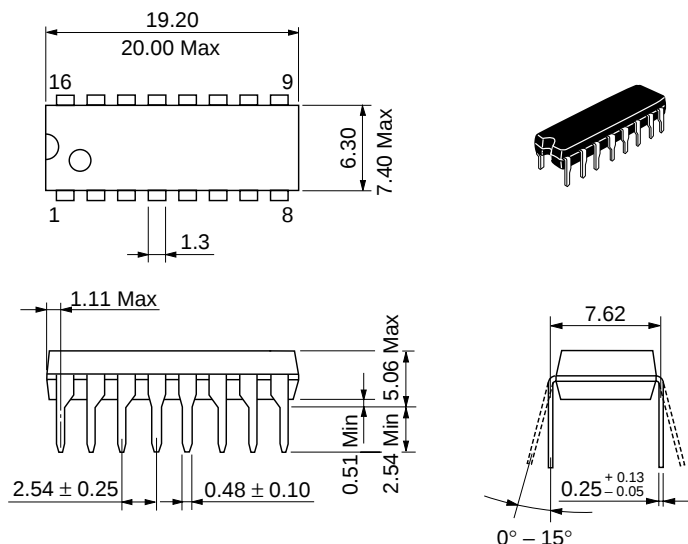
HD74HC138

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Item	Symbol	V _{CC} (V)	Ta = −40 to +85°C						Unit	Test Conditions
			Ta = 25°C							
			Min	Typ	Max	Min	Max			
Propagation delay time	t _{PHL}	2.0	—	—	175	—	220	ns	A, B or C to Output	
		4.5	—	17	35	—	44			
		6.0	—	—	30	—	37			
	t _{PLH}	2.0	—	—	150	—	190	ns		
		4.5	—	16	30	—	38			
		6.0	—	—	26	—	33			
	t _{PHL}	2.0	—	—	150	—	190	ns	G ₁ to Output	
		4.5	—	16	30	—	38			
		6.0	—	—	26	—	33			
	t _{PLH}	2.0	—	—	150	—	190	ns		
		4.5	—	17	30	—	38			
		6.0	—	—	26	—	33			
	t _{PHL}	2.0	—	—	175	—	220	ns	G _{2A} or G _{2B} to Output	
		4.5	—	15	35	—	44			
		6.0	—	—	30	—	37			
	t _{PLH}	2.0	—	—	150	—	190	ns		
		4.5	—	17	30	—	38			
		6.0	—	—	26	—	33			
Output rise/fall time	t _{TLH}	2.0	—	—	75	—	95	ns		
	t _{THL}	4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Input capacitance	C _{in}	—	—	5	10	—	10	pF		

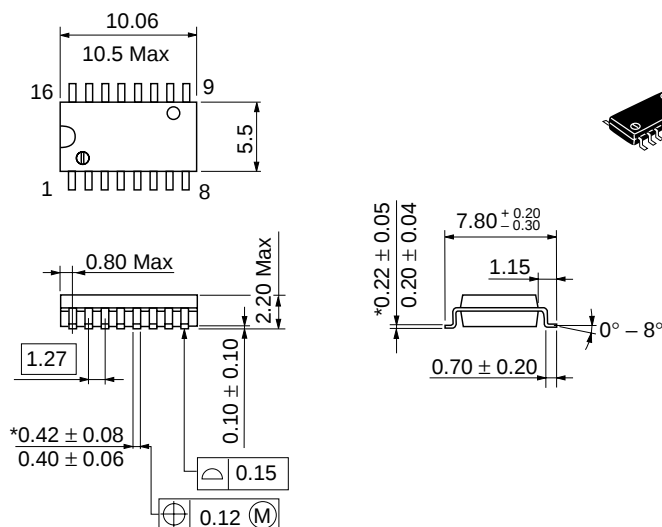
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

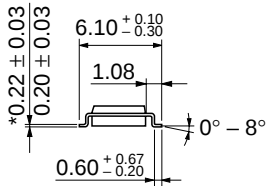
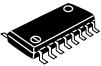
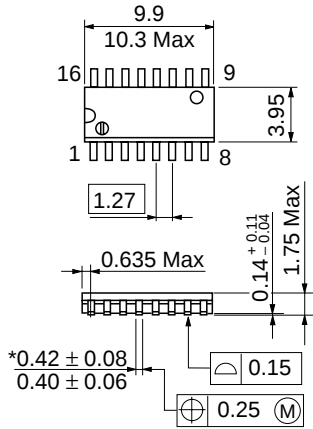
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

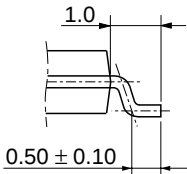
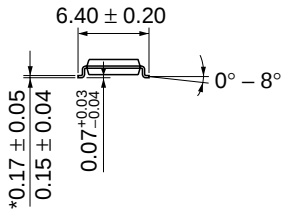
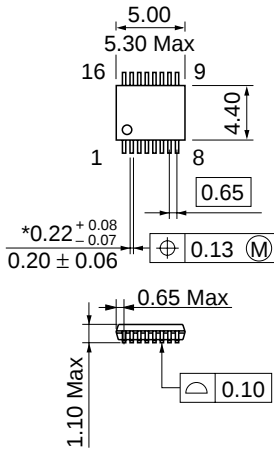
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-16DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.05 g

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